

PRESENTATION

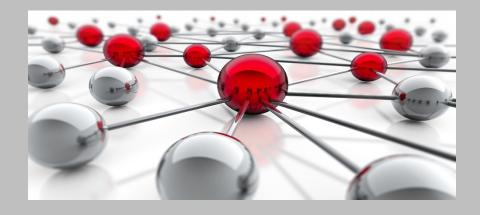
PRESENTER / DATE:



COMPETENCES & EXPERIENCE

• OFFERED PRODUCTS & SERVICES





ARE CON

is a **sales, service and consulting** organization within the smart card industry, targeting to connect business partners for mutual success.



ARE CON IN A NUTSHELL ... >50 / 25% / 2008



YEARS OF SMARDCARD INDUSTRY KNOWLEDGE



ANNUAL GROWTH RATE

YEAR OF FOUNDATION





COMPETENCES & EXPERIENCE

OFFERED PRODUCTS & SERVICES



COMPETENCES & EXPERIENCE

OUR STRENGTHS

- Long practical experience and know-how in different areas of the Smart Card Industry (card manufacturing / pre-press / personalization / security printing / technical consultancy etc.)
- Large international network
- Customer-oriented mentality
- Highest standards of quality
- Innovative and flexible thinking

YOUR ADVANTAGES

- Fast lead times
- Optimized and tailormade solutions
- Benefit from our experience and be one step ahead!





COMPETENCES & EXPERIENCE



Bernhard F. Wernberger

Managing Director

Experience:

- Managing Director at Novacard GmbH
- Manager BS IT/Access at Winter AG
- Management Consultant
- Director Sales EMEA at Power Integrations GmbH
- Account Manager Identification at NXP (Philips Semi.)
- Global Purchasing Coordinator at NXP (Philips Semi.)

Degree in Engineering & Business



COMPETENCES & EXPERIENCE



Anja Knitter

Head of Finance / Authorized Representative

Experience:

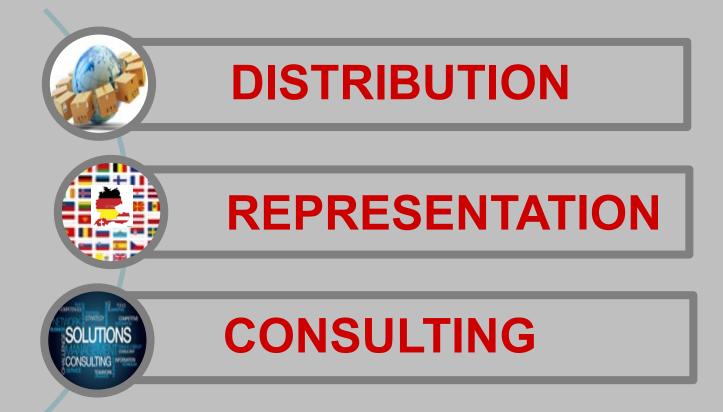
- Authorized Representative at Novacard GmbH
- Commercial Clerk at Novacard GmbH
- Order Preparation Card Manufacturing at Rothahn Essich GmbH



COMPETENCES & EXPERIENCE

• OFFERED PRODUCTS & SERVICES







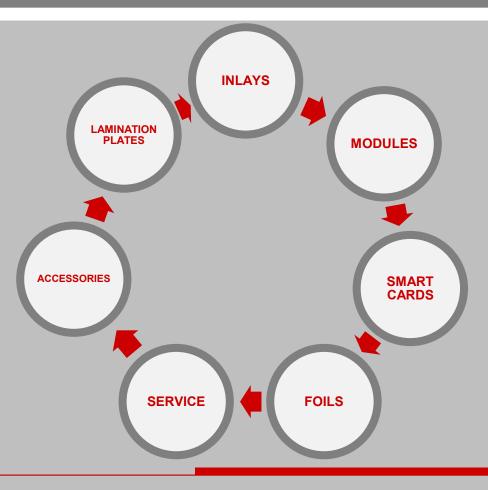


We offer components and semi-finished products around the smart card to

- Card manufacturers
- State printers
- Governmental organizations
- System integrators
- etc.



DISTRIBUTION





INLAYS

DISTRIBUTION

PRODUCT PORTFOLIO

- CUSTOMIZED FORMATS (3x6/3x7/3x8/2x5 etc.)
- DIFFERENT MATERIALS (PVC / PC / PET etc.)
- DIFFERENT THICKNESSES AND ANTENNA PROCESSINGS (embedded wire, etched antenna, direct bonding etc.)
- LF MODULES (*Hitag 1 / Hitag 2 / EM 4200 / ATA 5577 etc.*)
- HF MODULES (*Mifare Classic / Mifare DESFire / Legic / I-Code etc.*)
- UHF MODULES (Monza 4QT, U-Code, Alien-Higgs 3 etc.)
- HYBRID TECHNOLOGIES (combination of LF, HF, UHF, contact chips, magstripes, barcodes)



MODULES

DISTRIBUTION

PRODUCT PORTFOLIO

- Secure memory chips
- Crypto memory chips
- Microprocessor chips
- 6 or 8 contacts
- Selection of numerous packages, various adhesives for different card materials etc.
- Manufacturer: Microchip / Infineon, ATMEL, NXP etc.

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DISTRIBUTION

CONTACTLESS CARDS



- HF HIGH FREQUENCY MODULES
 NXP MIFARE Ultralight, NXP MIFARE Classic,
 NXP Mifare DESFire, NXP I-Code, LEGIC Prime, LEGIC Advant, LEGIC CTC etc.
- LF LOW FREQUENCY MODULES NXP Hitag 1, NXP Hitag 2, EM 4102, EM 4450, Atmel ATA5577 etc.
- UHF ULTRA HIGH FREQUENCY MODULES Impinj Monza 4QT, Alien-Higgs 3, NXP UCODE etc.
- NFC NEAR FIELD COMMUNICATION NXP NTAG203 etc.



DISTRIBUTION

CONTACT CARDS

MEMORY CARDS

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Secure Memories

- Atmel AT24C02- AT24C1024
- Microchip 24LC01-24LC512
- Infineon SLE 5532 / 5542 / 5552 / 5518 / 5528 / 5538

Crypto Memories

• Atmel AT88SC0104-AT88SC25616

MICROPROCESSOR CARDS

- NXP with JCOP OS / J1A020-J3D145
- Infineon with CardOS 4.4 / 5.0 SLE 66CX680PE 78CLX800P



DISTRIBUTION

HYBRID CARDS



COMBINATION OF VARIOUS TECHNOLOGIES ON ONE CARD

HF / LF / UHF / contact chips / magstripes / barcodes



DISTRIBUTION

COLLECTION OF FURTHER CARD FEATURES

- Special form factors
- Holograms
- Signature panel
- Scratch off panel
- Thermo-rewritable foil
- Punch holes
- Security printing
- Relief structures
- Etc.





FOILS

DISTRIBUTION

CORE MATERIAL + OVERLAYS

PVC / PET-G / PET-F / PVC-ABS / PC



OPTIONS

- Overlays with special coatings and surface qualities
- High VICAT values
- Selection of thicknesses from 45 μm up to 820 μm
- Quality varieties for different applications (credit cards, contactless cards, dual interface cards, standard and low cost cards)



SERVICE

DISTRIBUTION

PRINTING

- Thermal transfer printing
- Dye sublimation printing
- Embossing
- Re-transfer printing
- Inkjet Printing
- Laser Personalization

ENCODING

- Encoding of magstripes and barcodes
- Encoding of contact and contactless cards (LF/HF/Multi technologies)

FURTHER SERVICES

- Chip initialization / pre-personalization / programming
- Applet loading
- Layout & Pre-press service
- Mailing





ACCESSORIES

DISTRIBUTION

FURTHER RFID MEDIA

- Key fobs
- RFID / UHF / NFC labels
- RFID wristband
- Wearables
- CARD ACCESSORIES
- Lanyards
- Yo-Yos
- Clips
- Badge holder

CARD PRINTER

SEMI-FINISHED PRODUCTS





LAMINATION PLATES

DISTRIBUTION

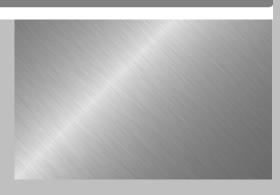
High quality lamination plates and pads for standard and security card manufacturing

LAMINATION PLATES

- Different surfaces: glossy / light matt / silk matt
- Tactile surface structures
- Special features: Braille lettering, microtext

LAMINATION PADS

Press pads for standard (155 °C) and high temperature lamination (215 °C)







ARE CON represents SMART PACKAGING SOLUTIONS (SPS),

Main provider of secure and high added value components for card and document manufacturers and World Leader in Dual Interface Banking and eID documents.







REPRESENTATION

PRODUCT LINE	eBoost PAY® For Banking & Transportation	eBoost ID® For eID cards	eBoost PASS® For ePassport
PRODUCTS	DUAL 6 DUAL 8	DUAL HYBRID CONTACT CONTACTLESS	INLAY eCOVER
	Inlay Prelam	Inlay Prelam	Inlay for Datapage Polycarbonate*
	SILVER GOLD	SILVER GOLD	Teslin Pflex
OPTIONS	CMI	CMI CAI	CMI CAI
		VMI*	VMI*
	Pre-personalization OS loading service	Pre-personalization OS loading service	Pre-personalization OS loading service
	Note		



CMI : customized module image CAI : customized antenna image VMI : variable module image * : under development





We offer **consultancy and business development services** for the government and smart card industry in purchasing, processing and sales of complex ID-related products.





PROCESS & COST ANALYSIS

ENGINEERING & SALES CONSULTANCY

TENDER PREPARATION



For further information please contact:

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QUESTIONS ?

